

## AMENDMENTS TO THE SPECIFICATION:

Page 4, lines 3 to 13, replace the paragraph:

“US Patent No. 6,075,699 issued in 2000 to W. Rife discloses a heatsink assembly with a retaining clip that has a central member and a number of legs which depending downwardly from the central member with ends of the legs not connected to the central member being free ends. Retention members are provided on each of the free ends of the legs to prevent the legs from being removed from their respective mounting holes. A heat dissipating member, having a threaded base portion is threadably received in a bore in the central member so that the flat bottom surface of the heat dissipating member is in flush thermal communication with the electronic component while the legs are secured within their respective holes in the electronic component. This device is also complicated in structure and occupies an extra space. If an extra pressure is accidentally applied to the chip through the threaded ~~heat-sink~~ heatsink, this can easily damage the chip.”

Page 9, lines 1 to 16, replace the paragraph:

In its simplest form, the invention is shown in Fig. 1B, which is a side sectional view of an assembly composed of two objects interconnected via a heat-shrinkable insert of the present invention. More specifically, an object, e.g., a plate 10a and another object, e.g., a plate 12a, are interconnected by an adhesive 14a that fills a space defined by the aforementioned plates 10a, 12a, and by strips 16a and 17a which are made from a heat-shrinkable material with unidirectional shrinkage in the direction shown by arrow A in Fig. 1B. The assembly is produced by sandwiching the strips 16a and 17a between the plates 10a and 12a, attaching, e.g., ~~by glue~~ by glue layers 19a and 21a, both sides of the strips 16a and 17a to respective plates 10a, 12a, filling the space defined by the plates 10a, 12a, and the strips 16a, 17a with an adhesive agent 14a, and heating the assembly or preferably only the strips 16a, 17a in order to cause shrinking of the strips. In order to compensate for the compression of the adhesive substance 14a caused by mutual approach of the plates due to shrinking of the strips 16a, 17a to which the plates are attached, the volume of the adhesive 14a should be less than the volume of the

aforementioned closed space, or the side walls of the strips should be resilient in the direction perpendicular to the direction of shrinkage.

Page 10, lines 12 to 15, replace the paragraph:

“One side, e.g., side 34a, of the heat shrinkable spacer ~~32~~ 34 is attached, e.g., glued via an adhesive substance 46 to the support surface 38 of the ~~heat~~ heat sink 30. The opposite side, e.g., side 34b, of the heat shrinkable spacer ~~32~~ 34 is attached, e.g., glued via an adhesive substance 48, to the surface of the support or PC board 33.”

Page 10, lines 16 to 26, replace the paragraph:

“Fig. 3 is a cross-sectional view along the line III-III of Fig. 2 that illustrates an example of a cross sectional shape of the heat-shrinkable insert 34. In Figs. 2 and. 3, the heat shrinkable spacer ~~32~~ 34 is shown as a hollow body with two side walls 34c and 34d thicker than two other side walls 34e, 34f that are arranged in the direction of stretching of the insert’s material and hence in the direction of thermal shrinking shown by arrows A. If necessary, the hollow insert may have a rigidity rib ~~34g~~ (not shown). The cross-sectional configuration of the heat-shrinkable insert is not limited to the hollow shape shown in Fig. 3, and the insert can be extruded in the form of a solid block 35, e.g., of a rectangular cross section, provided that it can be shrinkable by heating in one direction, e.g., a direction perpendicular to the surfaces of the heatsink and the PC board 33. An example of such a shape is shown in Fig. 4.”

Page 11, lines 1 to 15, replace the paragraph:

“It can be seen from Fig. 2 that the height of the spacer 34, e.g., the distance H2 between the support surface 38 of the heatsink 30 and the support base or PC board 33 is greater than the height H1 of the object or electronic chip 32. The difference between the aforementioned heights, i.e., the distance H4, in turn, should be smaller than the amount of shrinkage H3 of the spacer 34 in the shrinkage direction shown by arrow A, so that shrinkage of the spacer 34 under the effect of heating could press the support surface 38 of the ~~heatsink~~ heatsink 30 to the facing surface 40 of the electronic chip 32 with a reliable force which is proportional to the interference fit conventionally shown in Fig. 2

as a distance H4. In Fig. 2, a spacer 34' drawn by dashed lines shows an imaginary view of the spacer 34 if it were be shrunk in a free state. For the simplicity of the explanation, the thickness of the glue layers and deviations of the dimensions within the allowed tolerances, etc., are not taken into consideration. The height H2 of the insert 34 may be standardizes so that the insert 34 may be produced as an elongated body and then cut off to required dimensions in the longitudinal direction of the molded or extruded product."